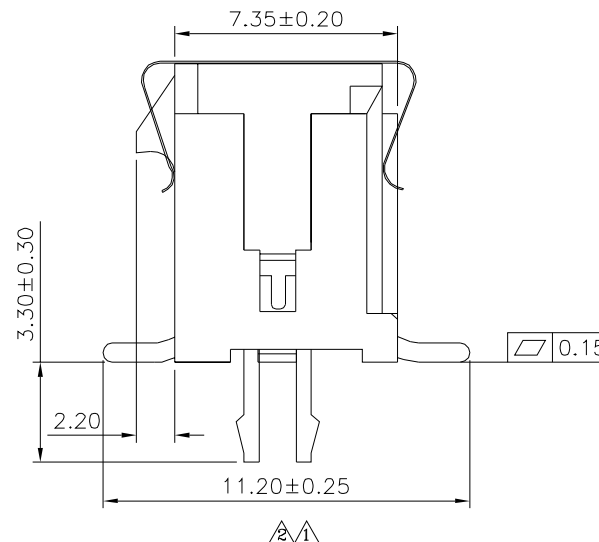
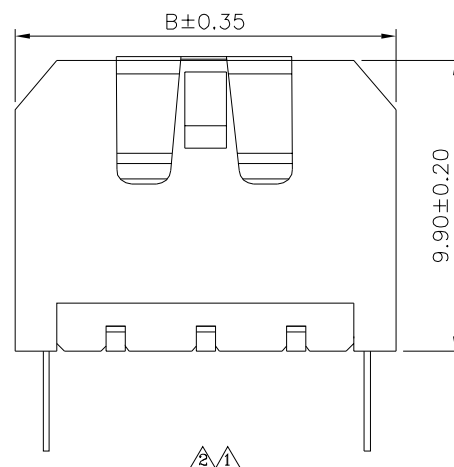
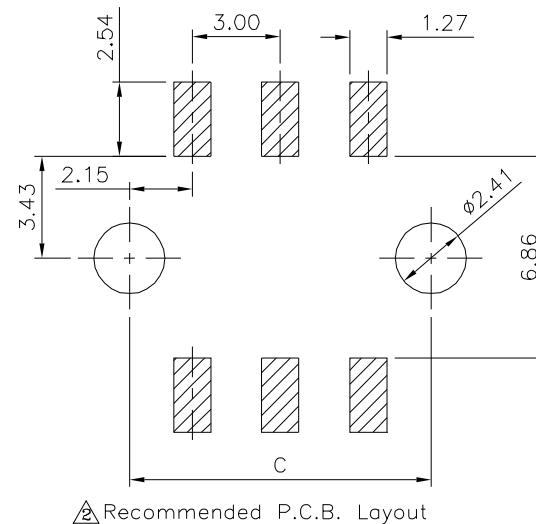
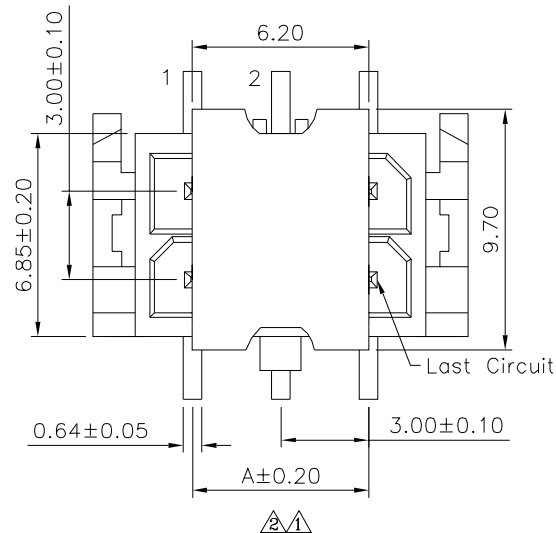


SPECIFICATION

- General Characteristics**
3.0mm Micro-Fit Wafer 2XXX SMT 180°
With DIP Boardlock Black Insulator Tin Plated
With Cap Tape&Reel 200 PCS/Reel
- Material&Finish**
Housing:LCP(UL94V-0),Black
Contact:Brass,Tin Plated
Solder Tabs:Brass
Cap:Stainless Steel
- Electrical Characteristics**
Current Rating:5A AC/DC
Voltage Rating:250V AC/DC
Contact Resistance:20 Milliohms Max.
Insulation Resistance:1000 Megaohms Min.
Withstand Voltage:1500V AC/Minute
- Environmental Characteristics**
Temperature Range:-25°C~+85°C
- RoHS Compliant**



Pin	A	B	C
02		6.65	4.30
04	3.00	9.65	7.30
06	6.00	12.65	10.30
08	9.00	15.65	13.30
10	12.00	18.65	16.30
12	15.00	21.65	19.30
14	18.00	24.65	22.30
16	21.00	27.65	25.30
18	24.00	30.65	28.30
20	27.00	33.65	31.30
22	30.00	36.65	34.30
24	33.00	39.65	37.30

4UCON 元化興業股份有限公司
4UCON TECHNOLOGY INC.

DRAWING No.

06372

SCALE NONE

APPROVED BY

MEI

CHECKED BY

HZF

DRAWING BY

CYP

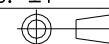
REV.

A2

UNLESS OTHERWISE
SPECIFIED
TOLERANCES ARE

X. ±0.30
.X ±0.25
.XX ±0.20
.XXX ±0.05
ANG. ±1°

UNIT
mm



NO.	REV.	REVISIONS	CHK	DATE
A2		Modify Data	HZF	12/26/2017
A1		Modify Data	HZF	12/22/2014
A0		NEW RELEASE	HZF	11/02/2012

